

In the Specification:

Please replace paragraphs [0005] and [0018] as follows:

[0005] The invention relates to a method for manufacturing plate stacks, for the production of coolers, cooler elements or heat sinks comprising at least one plate stack for cooling electric and/or opto-electric components, wherein the method comprises at least the following process steps: manufacture of plates or boards of metal, stacking of the plates to form a plate stack, joining of the plates with the application of heat at a mechanic pressing force between 20 and 2500 bar and at a joining temperature (IF) and at an atmospheric pressure or in a vacuum, cooling of the plate stack formed by the joined plates to a temperature below the joining temperature (IF) and post-treatment (HIP treatment) of the plates stack in an inert gas atmosphere at an inert gas pressure (PB) between 200 and 2000 bar, and at a post-treatment temperature (TB) that is below the joining temperature (IF).

[0018] In a preferable embodiment the oxygen content of the inert gas atmosphere is no more than approximately 300 % of the equilibrium oxygen partial pressure of the metal used at the respective treatment temperature TB. The use of copper plates results in an oxygen content and oxygen partial pressure based on the temperature according to the following table: